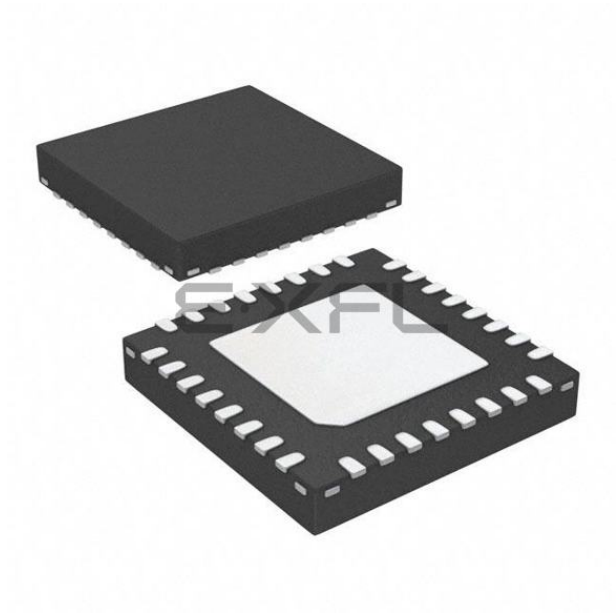

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	28
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VQFN Exposed Pad
Supplier Device Package	32-HVQFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1114fhn33-303y

- Digital peripherals:
  - Up to 42 General Purpose I/O (GPIO) pins with configurable pull-up/pull-down resistors. In addition, a configurable open-drain mode is supported on the LPC1100L and LPC1100XL series.
  - GPIO pins can be used as edge and level sensitive interrupt sources.
  - High-current output driver (20 mA) on one pin.
  - High-current sink drivers (20 mA) on two I^2C-bus pins in Fast-mode Plus (not on LPC1112FDH20/102).
  - Four general purpose counter/timers with up to eight capture inputs and up to 13 match outputs.
  - Programmable WatchDog Timer (WDT) the LPC1100 series only.
  - Programmable windowed WDT on the LPC1100L and LPC1100XL series only.
- Analog peripherals:
  - 10-bit ADC with input multiplexing among 5, 6, or 8 pins depending on package size.
- Serial interfaces:
  - UART with fractional baud rate generation, internal FIFO, and RS-485 support.
  - Two SPI controllers with SSP features and with FIFO and multi-protocol capabilities (second SPI on LPC1100 and LPC1100L series LQFP48 package only).
  - I^2C-bus interface supporting full I^2C-bus specification and Fast-mode Plus with a data rate of 1 Mbit/s with multiple address recognition and monitor mode (not on LPC1112FDH20/102).
- Clock generation:
  - 12 MHz internal RC oscillator trimmed to 1 % accuracy that can optionally be used as a system clock.
  - Crystal oscillator with an operating range of 1 MHz to 25 MHz.
  - Programmable watchdog oscillator with a frequency range of 9.4 kHz to 2.3 MHz.
  - PLL allows CPU operation up to the maximum CPU rate without the need for a high-frequency crystal. May be run from the system oscillator or the internal RC oscillator.
  - Clock output function with divider that can reflect the system oscillator clock, IRC clock, CPU clock, and the Watchdog clock.
- Power control:
  - Integrated PMU (Power Management Unit) to minimize power consumption during Sleep, Deep-sleep, and Deep power-down modes.
  - Power profiles residing in boot ROM allowing to optimize performance and minimize power consumption for any given application through one simple function call. (LPC1100L and LPC1100XL series only.)
  - Three reduced power modes: Sleep, Deep-sleep, and Deep power-down.
  - Processor wake-up from Deep-sleep mode via a dedicated start logic using up to 13 of the functional pins.
  - Power-On Reset (POR).
  - Brownout detect with up to four separate thresholds for interrupt and forced reset.
- Unique device serial number for identification.
- Single power supply (1.8 V to 3.6 V).
- Available as LQFP48 package, HVQFN33 package, and TFBGA48 package.

Table 1. Ordering information *…continued*

Type number	Package		
	Name	Description	Version
LPC1114FHI33/302	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1114FHI33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1114JHI33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 5 × 5 × 0.85 mm	n/a
LPC1114FHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114JHN33/203	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114FHN33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114JHN33/303	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114FHN33/333	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1114JHN33/333	HVQFN33	HVQFN: plastic thermal enhanced very thin quad flat package; no leads; 33 terminals; body 7 × 7 × 0.85 mm	n/a
LPC1113FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1113FBD48/302	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1113FBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1113JBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/302	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114JBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/323	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114JBD48/323	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114FBD48/333	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1114JBD48/333	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1115FBD48/303	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2

Table 2. Ordering options *…continued*

Type number	Series	Flash	Total SRAM	Power profiles	UART	I^2C/ Fast+	SPI	ADC channel	GPIO	Package	Temp[1]
LPC1115JBD48/303	LPC1100XL	64 kB	8 kB	yes	1	1	2	8	42	LQFP48	J
LPC1115FET48/303	LPC1100XL	64 kB	8 kB	yes	1	1	2	8	42	TFBGA48	F
LPC1115JET48/303	LPC1100XL	64 kB	8 kB	yes	1	1	2	8	42	TFBGA48	J

[1] F = −40 °C to +85 °C, J = −40 °C to +105 °C.

6. Pinning information

6.1 Pinning

Table 3. Pin description overview

Part	Pin description table	Pinning diagram
LPC1110FD20	Table 4	Figure 8
LPC1111FDH20/002	Table 4	Figure 9
LPC1112FD20/102	Table 4	Figure 10
LPC1112FDH20/102	Table 5	Figure 9
LPC1112FHN24/202	Table 6	Figure 11
LPC1112FDH28/102	Table 7	Figure 12
LPC1114FDH28/102	Table 7	Figure 13
LPC1114FN28/102	Table 7	Figure 13
LPC1111FHN33/101	Table 9	Figure 6
LPC1111FHN33/102	Table 9	Figure 6
LPC1111JHN33/103	Table 11	Figure 7
LPC1111FHN33/103	Table 11	Figure 7
LPC1111FHN33/201	Table 9	Figure 6
LPC1111FHN33/202	Table 9	Figure 6
LPC1111FHN33/203	Table 11	Figure 7
LPC1111JHN33/203	Table 11	Figure 7
LPC1112FHN33/101	Table 9	Figure 6
LPC1112FHN33/102	Table 9	Figure 6
LPC1112FHN33/103	Table 11	Figure 7
LPC1112JHN33/103	Table 11	Figure 7
LPC1112FHN33/201	Table 9	Figure 6
LPC1112FHN33/202	Table 9	Figure 6
LPC1112FHN33/203	Table 11	Figure 7
LPC1112JHN33/203	Table 11	Figure 7
LPC1112FHI33/202	Table 9	Figure 6
LPC1112FHI33/203	Table 11	Figure 7
LPC1112JHI33/203	Table 11	Figure 7
LPC1113FHN33/201	Table 9	Figure 6
LPC1113FHN33/202	Table 9	Figure 6
LPC1113FHN33/203	Table 11	Figure 7
LPC1113JHN33/203	Table 11	Figure 7
LPC1113FHN33/301	Table 9	Figure 6
LPC1113FHN33/302	Table 9	Figure 6
LPC1113FHN33/303	Table 11	Figure 7
LPC1113JHN33/303	Table 11	Figure 7
LPC1114FHN33/201	Table 9	Figure 6
LPC1114FHN33/202	Table 9	Figure 6

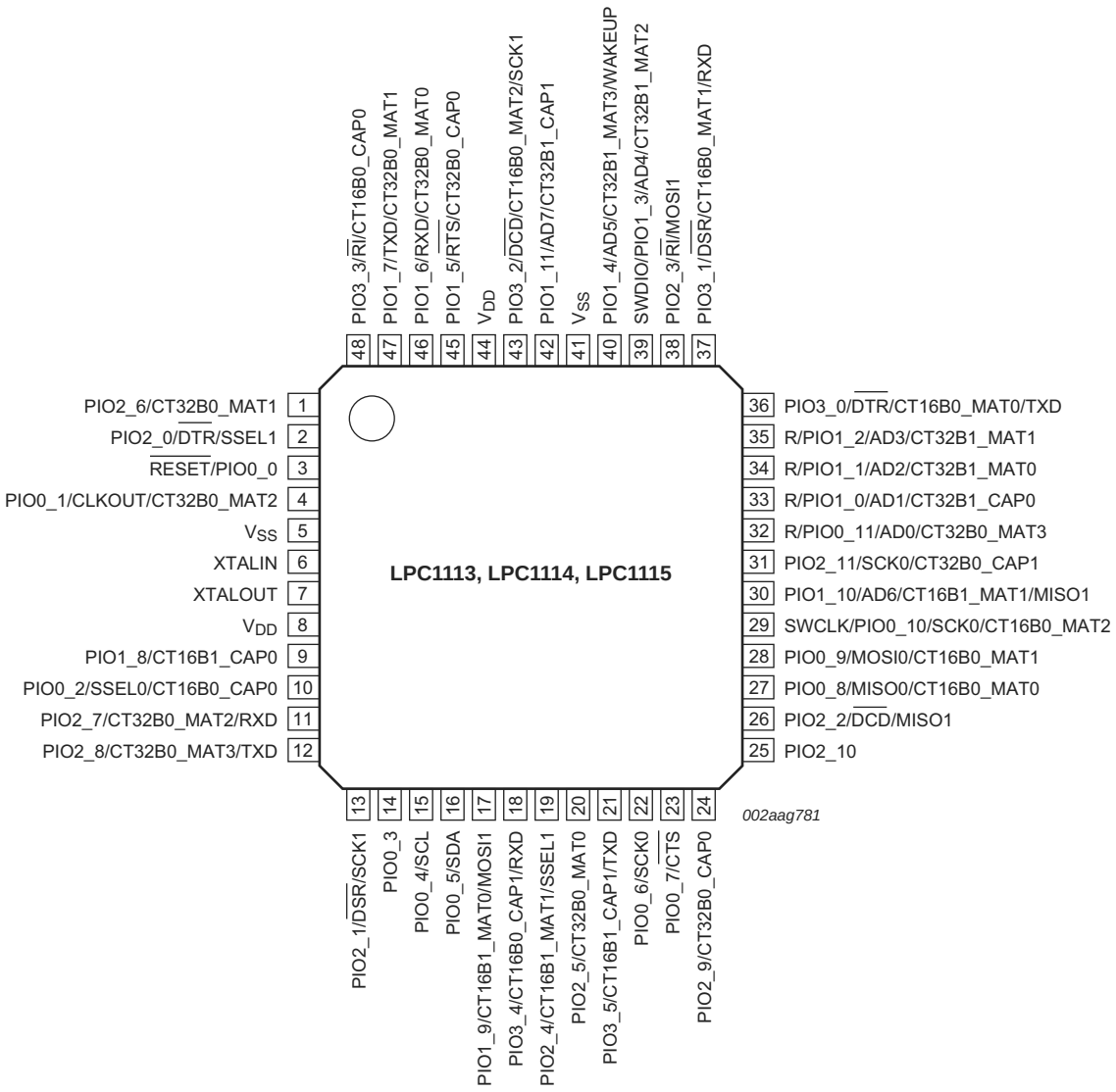


Fig 4. LPC1100XL series pin configuration LQFP48 package

Table 6. LPC1100L series: LPC1112 (HVQFN24 package) *…continued*

Symbol	HVQFN pin	Start logic input	Type	Reset state [1]	Description
SWDIO/PIO1_3/ AD4/CT32B1_MAT2	19[5]	no	I/O	I; PU	**SWDIO —** Serial wire debug input/output.
			I/O	-	**PIO1_3 —** General purpose digital input/output pin.
			I	-	**AD4 —** A/D converter, input 4.
			O	-	**CT32B1_MAT2 —** Match output 2 for 32-bit timer 1.
PIO1_4/AD5/ CT32B1_MAT3/ WAKEUP	20[5]	no	I/O	I; PU	**PIO1_4 —** General purpose digital input/output pin with 10 ns glitch filter. In Deep power-down mode, this pin serves as the Deep power-down mode wake-up pin with 20 ns glitch filter. Pull this pin HIGH externally before entering Deep power-down mode. Pull this pin LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.
			I	-	**AD5 —** A/D converter, input 5.
			O	-	**CT32B1_MAT3 —** Match output 3 for 32-bit timer 1.
PIO1_6/RXD/ CT32B0_MAT0	23[3]	no	I/O	I; PU	**PIO1_6 —** General purpose digital input/output pin.
			I	-	**RXD —** Receiver input for UART.
			O	-	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO1_7/TXD/ CT32B0_MAT1	24[3]	no	I/O	I; PU	**PIO1_7 —** General purpose digital input/output pin.
			O	-	**TXD —** Transmitter output for UART.
			O	-	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO1_8/ CT16B1_CAP0	6[3]	no	I/O	I; PU	**PIO1_8 —** General purpose digital input/output pin.
			I	-	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
XTALIN	4[6]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
V_{DD}	5; 22	-	I	-	1.8 V supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
V_{SS}	3; 21	-	I	-	Ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (pins pulled up to full V_{DD} level); IA = inactive, no pull-up/down enabled.

[2] 5 V tolerant pad. $\overline{\text{RESET}}$ functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See Figure 52 for the reset pad configuration.

[3] Pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 51).

[4] I^2C-bus pads compliant with the I^2C-bus specification for I^2C standard mode and I^2C Fast-mode Plus. The pin requires an external pull-up to provide output functionality. When power is switched off, this pin is floating and does not disturb the I2C lines. Open-drain configuration applies to all functions on this pin.

[5] Pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled (see Figure 51).

[6] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

Table 8. LPC1100 and LPC1100L series: LPC1113/14 pin description table (LQFP48 package) *…continued*

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
SWCLK/PIO0_10/ SCK0/ CT16B0_MAT2	29[3]	yes	I	I; PU	**SWCLK —** Serial wire clock.
			I/O	-	**PIO0_10 —** General purpose digital input/output pin.
			I/O	-	**SCK0 —** Serial clock for SPI0.
			O	-	**CT16B0_MAT2 —** Match output 2 for 16-bit timer 0.
R/PIO0_11/ AD0/CT32B0_MAT3	32[5]	yes	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO0_11 —** General purpose digital input/output pin.
			I	-	**AD0 —** A/D converter, input 0.
			O	-	**CT32B0_MAT3 —** Match output 3 for 32-bit timer 0.
PIO1_0 to PIO1_11			I/O		**Port 1 —** Port 1 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 1 pins depends on the function selected through the IOCONFIG register block.
R/PIO1_0/ AD1/CT32B1_CAP0	33[5]	yes	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_0 —** General purpose digital input/output pin.
			I	-	**AD1 —** A/D converter, input 1.
			I	-	**CT32B1_CAP0 —** Capture input 0 for 32-bit timer 1.
R/PIO1_1/ AD2/CT32B1_MAT0	34[5]	no	O	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_1 —** General purpose digital input/output pin.
			I	-	**AD2 —** A/D converter, input 2.
			O	-	**CT32B1_MAT0 —** Match output 0 for 32-bit timer 1.
R/PIO1_2/ AD3/CT32B1_MAT1	35[5]	no	I	I; PU	**R —** Reserved. Configure for an alternate function in the IOCONFIG block.
			I/O	-	**PIO1_2 —** General purpose digital input/output pin.
			I	-	**AD3 —** A/D converter, input 3.
			O	-	**CT32B1_MAT1 —** Match output 1 for 32-bit timer 1.
SWDIO/PIO1_3/ AD4/CT32B1_MAT2	39[5]	no	I/O	I; PU	**SWDIO —** Serial wire debug input/output.
			I/O	-	**PIO1_3 —** General purpose digital input/output pin.
			I	-	**AD4 —** A/D converter, input 4.
			O	-	**CT32B1_MAT2 —** Match output 2 for 32-bit timer 1.
PIO1_4/AD5/ CT32B1_MAT3/ WAKEUP	40[5]	no	I/O	I; PU	**PIO1_4 —** General purpose digital input/output pin with 10 ns glitch filter. In Deep power-down mode, this pin serves as the Deep power-down mode wake-up pin with 20 ns glitch filter. Pull this pin HIGH externally before entering Deep power-down mode. Pull this pin LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.
			I	-	**AD5 —** A/D converter, input 5.
			O	-	**CT32B1_MAT3 —** Match output 3 for 32-bit timer 1.
PIO1_5/$\overline{\text{RTS}}$/ CT32B0_CAP0	45[3]	no	I/O	I; PU	**PIO1_5 —** General purpose digital input/output pin.
			O	-	**$\overline{\text{RTS}}$ —** Request To Send output for UART.
			I	-	**CT32B0_CAP0 —** Capture input 0 for 32-bit timer 0.

Table 8. LPC1100 and LPC1100L series: LPC1113/14 pin description table (LQFP48 package) *…continued*

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
PIO1_6/RXD/ CT32B0_MAT0	46[3]	no	I/O	I; PU	**PIO1_6 —** General purpose digital input/output pin.
			I	-	**RXD —** Receiver input for UART.
			O	-	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO1_7/TXD/ CT32B0_MAT1	47[3]	no	I/O	I; PU	**PIO1_7 —** General purpose digital input/output pin.
			O	-	**TXD —** Transmitter output for UART.
			O	-	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO1_8/ CT16B1_CAP0	9[3]	no	I/O	I; PU	**PIO1_8 —** General purpose digital input/output pin.
			I	-	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
PIO1_9/ CT16B1_MAT0	17[3]	no	I/O	I; PU	**PIO1_9 —** General purpose digital input/output pin.
			O	-	**CT16B1_MAT0 —** Match output 0 for 16-bit timer 1.
PIO1_10/AD6/ CT16B1_MAT1	30[5]	no	I/O	I; PU	**PIO1_10 —** General purpose digital input/output pin.
			I	-	**AD6 —** A/D converter, input 6.
			O	-	**CT16B1_MAT1 —** Match output 1 for 16-bit timer 1.
PIO1_11/AD7	42[5]	no	I/O	I; PU	**PIO1_11 —** General purpose digital input/output pin.
			I	-	**AD7 —** A/D converter, input 7.
PIO2_0 to PIO2_11			I/O		**Port 2 —** Port 2 is a 12-bit I/O port with individual direction and function controls for each bit. The operation of port 2 pins depends on the function selected through the IOCONFIG register block.
PIO2_0/$\overline{\text{DTR}}$/SSEL1	2[3]	no	I/O	I; PU	**PIO2_0 —** General purpose digital input/output pin.
			O	-	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for UART.
			I/O	-	**SSEL1 —** Slave Select for SPI1.
PIO2_1/$\overline{\text{DSR}}$/SCK1	13[3]	no	I/O	I; PU	**PIO2_1 —** General purpose digital input/output pin.
			I	-	**$\overline{\text{DSR}}$ —** Data Set Ready input for UART.
			I/O	-	**SCK1 —** Serial clock for SPI1.
PIO2_2/$\overline{\text{DCD}}$/MISO1	26[3]	no	I/O	I; PU	**PIO2_2 —** General purpose digital input/output pin.
			I	-	**$\overline{\text{DCD}}$ —** Data Carrier Detect input for UART.
			I/O	-	**MISO1 —** Master In Slave Out for SPI1.
PIO2_3/$\overline{\text{RI}}$/MOSI1	38[3]	no	I/O	I; PU	**PIO2_3 —** General purpose digital input/output pin.
			I	-	**$\overline{\text{RI}}$ —** Ring Indicator input for UART.
			I/O	-	**MOSI1 —** Master Out Slave In for SPI1.
PIO2_4	19[3]	no	I/O	I; PU	**PIO2_4 —** General purpose digital input/output pin.
PIO2_5	20[3]	no	I/O	I; PU	**PIO2_5 —** General purpose digital input/output pin.
PIO2_6	1[3]	no	I/O	I; PU	**PIO2_6 —** General purpose digital input/output pin.
PIO2_7	11[3]	no	I/O	I; PU	**PIO2_7 —** General purpose digital input/output pin.
PIO2_8	12[3]	no	I/O	I; PU	**PIO2_8 —** General purpose digital input/output pin.
PIO2_9	24[3]	no	I/O	I; PU	**PIO2_9 —** General purpose digital input/output pin.
PIO2_10	25[3]	no	I/O	I; PU	**PIO2_10 —** General purpose digital input/output pin.
PIO2_11/SCK0	31[3]	no	I/O	I; PU	**PIO2_11 —** General purpose digital input/output pin.
			I/O	-	**SCK0 —** Serial clock for SPI0.

Table 11. LPC1100XL series: LPC1111/12/13/14 pin description table (HVQFN33 package) *…continued*

Symbol	Pin	Start logic input	Type	Reset state [1]	Description
V_{DD}	6; 29	-	I	-	3.3 V supply voltage to the internal regulator, the external rail, and the ADC. Also used as the ADC reference voltage.
XTALIN	4[6]	-	I	-	Input to the oscillator circuit and internal clock generator circuits. Input voltage must not exceed 1.8 V.
XTALOUT	5[6]	-	O	-	Output from the oscillator amplifier.
V_{SS}	33	-	-	-	Thermal pad. Connect to ground.

[1] Pin state at reset for default function: I = Input; O = Output; PU = internal pull-up enabled (pins pulled up to full V_{DD} level (V_{DD} = 3.3 V)); IA = inactive, no pull-up/down enabled.

[2] 5 V tolerant pad. $\overline{\text{RESET}}$ functionality is not available in Deep power-down mode. Use the WAKEUP pin to reset the chip and wake up from Deep power-down mode. An external pull-up resistor is required on this pin for the Deep power-down mode. See Figure 52 for the reset pad configuration.

[3] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors and configurable hysteresis (see Figure 51).

[4] I^2C-bus pads compliant with the I^2C-bus specification for I^2C standard mode and I^2C Fast-mode Plus. The pin requires an external pull-up to provide output functionality. When power is switched off, this pin is floating and does not disturb the I2C lines. Open-drain configuration applies to all functions on this pin.

[5] 5 V tolerant pad providing digital I/O functions with configurable pull-up/pull-down resistors, configurable hysteresis, and analog input. When configured as a ADC input, digital section of the pad is disabled, and the pin is not 5 V tolerant (see Figure 51).

[6] When the system oscillator is not used, connect XTALIN and XTALOUT as follows: XTALIN can be left floating or can be grounded (grounding is preferred to reduce susceptibility to noise). XTALOUT should be left floating.

- On the LPC1100L and LPC1100XL series, all GPIO pins (except PIO0_4 and PIO0_5) are pulled up to 3.3 V (V_{DD} = 3.3 V) if their pull-up resistor is enabled in the IOCONFIG block.
- Programmable open-drain mode for series LPC1100L and LPC1100XL.

7.8 UART

The LPC1110/11/12/13/14/15 contain one UART.

Support for RS-485/9-bit mode allows both software address detection and automatic address detection using 9-bit mode.

The UART includes a fractional baud rate generator. Standard baud rates such as 115200 Bd can be achieved with any crystal frequency above 2 MHz.

7.8.1 Features

- Maximum UART data bit rate of 3.125 MBit/s.
- 16 Byte Receive and Transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B.
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- FIFO control mechanism that enables software flow control implementation.
- Support for RS-485/9-bit mode.
- Support for modem control.

7.9 SPI serial I/O controller

The LPC1100 and LPC1100L series contain two SPI controllers on the LQFP48 package and one SPI controller on the HVQFN33/TSSOP28/DIP28/TSSOP20/SO20 packages (SPI0).

The LPC1100XL series contain two SPI controllers.

Both SPI controllers support SSP features.

The SPI controller is capable of operation on a SSP, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the bus during a given data transfer. The SPI supports full duplex transfers, with frames of 4 bits to 16 bits of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.9.1 Features

- Maximum SPI speed of 25 Mbit/s (master) or 4.17 Mbit/s (slave) (in SSP mode)
- Compatible with Motorola SPI, 4-wire Texas Instruments SSI, and National Semiconductor Microwire buses
- Synchronous serial communication

- Master or slave operation
- 8-frame FIFOs for both transmit and receive
- 4-bit to 16-bit frame

7.10 I²C-bus serial I/O controller

The LPC1110/11/12/13/14/15 contain one I²C-bus controller.

Remark: Part LPC1112FDH20/102 does not contain the I²C-bus controller.

The I²C-bus is bidirectional for inter-IC control using only two wires: a Serial Clock Line (SCL) and a Serial DAta line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I²C is a multi-master bus and can be controlled by more than one bus master connected to it.

7.10.1 Features

- The I²C-interface is a standard I²C-bus compliant interface with open-drain pins. The I²C-bus interface also supports Fast-mode Plus with bit rates up to 1 Mbit/s.
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I²C-bus can be used for test and diagnostic purposes.
- The I²C-bus controller supports multiple address recognition and a bus monitor mode.

7.11 10-bit ADC

The LPC1110/11/12/13/14/15 contain one ADC. It is a single 10-bit successive approximation ADC with eight channels.

7.11.1 Features

- 10-bit successive approximation ADC.
- Input multiplexing among 8 pins.
- Power-down mode.
- Measurement range 0 V to V_{DD}.
- 10-bit conversion time $\geq$ 2.44 μs (up to 400 kSamples/s).
- Burst conversion mode for single or multiple inputs.

Following reset, the LPC1110/11/12/13/14/15 will operate from the Internal RC oscillator until switched by software. This allows systems to operate without any external crystal and the bootloader code to operate at a known frequency.

See Figure 16 for an overview of the LPC1110/11/12/13/14/15 clock generation.

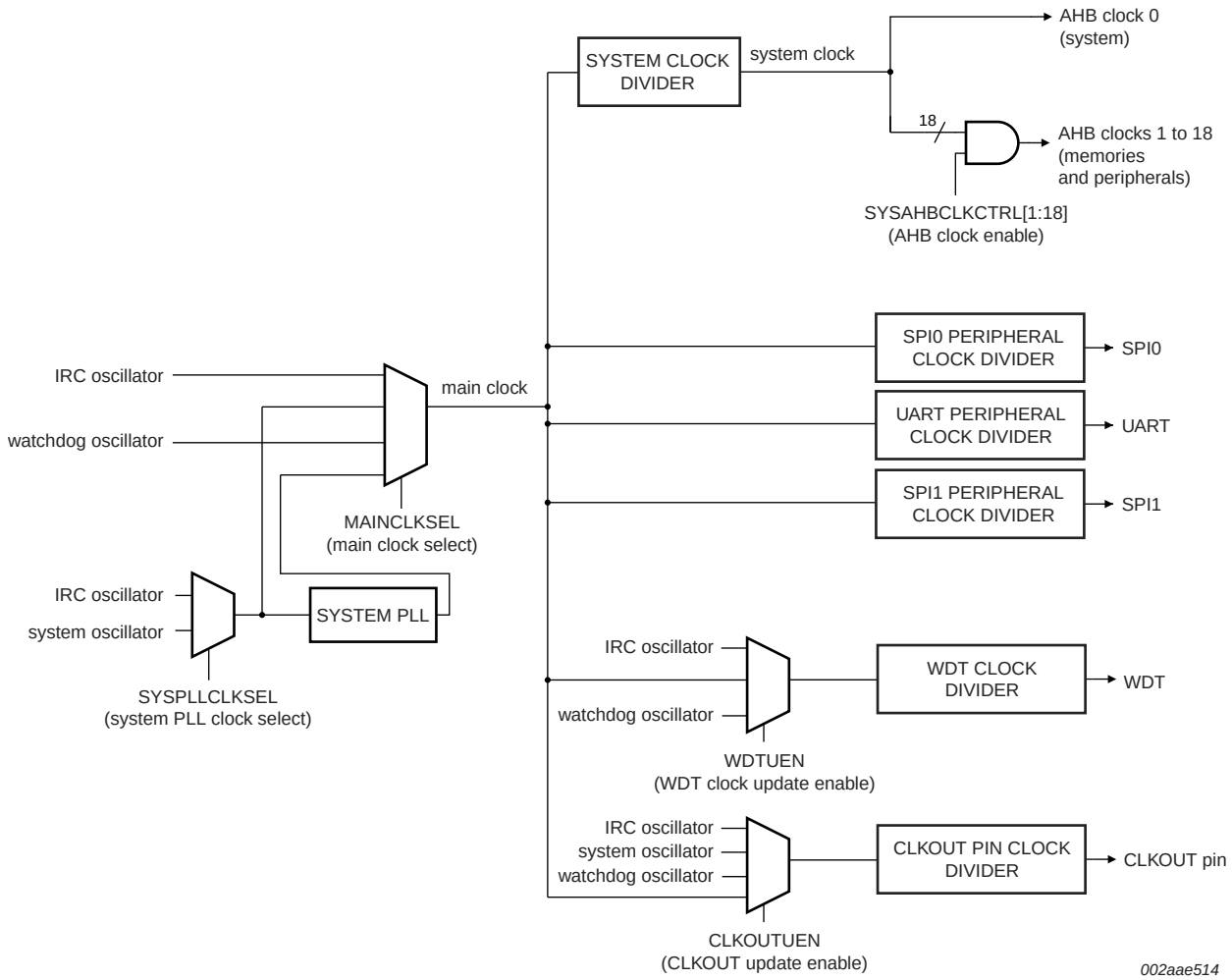


Fig 16. LPC1110/11/12/13/14/15 clock generation block diagram

7.16.1.1 Internal RC oscillator

The IRC may be used as the clock source for the WDT, and/or as the clock that drives the PLL and subsequently the CPU. The nominal IRC frequency is 12 MHz. The IRC is trimmed to 1 % accuracy over the entire voltage and temperature range.

Upon power-up or any chip reset, the LPC1110/11/12/13/14/15 use the IRC as the clock source. Software may later switch to one of the other available clock sources.

7.16.1.2 System oscillator

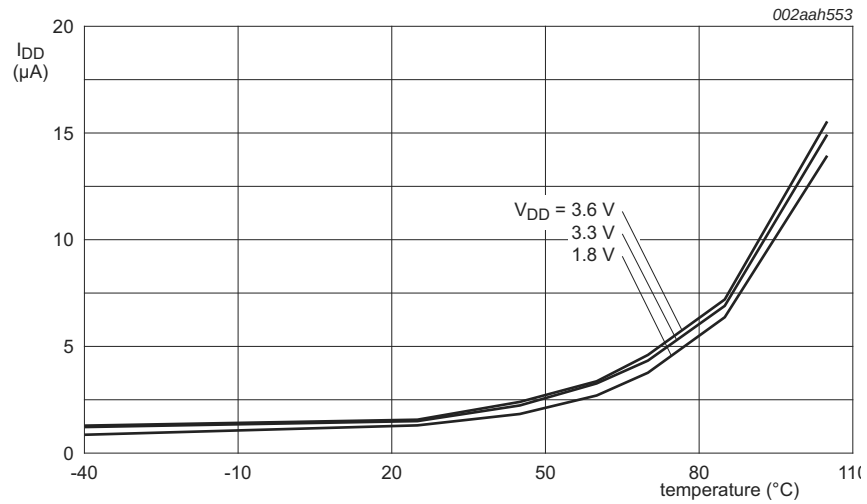
The system oscillator can be used as the clock source for the CPU, with or without using the PLL.

10.2 LPC1100XL series

Table 17. Static characteristics (LPC1100XL series)

T_{amb} = −40 °C to +105 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
V_{DD}	supply voltage (core and external rail)		1.8	3.3	3.6	V
LPC1100XL series (LPC111x/103/203/303/323/333) power consumption in low-current mode[2]						
I_{DD}	supply current	Active mode; code `while(1){}` executed from flash				
		system clock = 3 MHz; V_{DD} = 3.3 V [3][4][5][6][7]	-	600	-	μA
		system clock = 6 MHz; V_{DD} = 3.3 V [3][4][5][6][7]	-	850	-	μA
		system clock = 12 MHz; V_{DD} = 3.3 V [3][4][6][7][8]	-	1.4	-	mA
		system clock = 50 MHz; V_{DD} = 3.3 V [3][4][6][7][9]	-	5.8	-	mA
		Sleep mode; system clock = 12 MHz; V_{DD} = 3.3 V [3][4][6][7][8]	-	700	-	μA
		system clock = 50 MHz; V_{DD} = 3.3 V [3][4][6][7][8]	-	2.2	-	mA
		Deep-sleep mode; V_{DD} = 3.3 V; 25 °C [3][4][10]	-	1.8	15	μA
		Deep-sleep mode; V_{DD} = 3.3 V; 105 °C [4][10][11]	-	-	50	μA
		Deep power-down mode; V_{DD} = 3.3 V; 25 °C [3][12]	-	220	1000	nA
		Deep power-down mode; V_{DD} = 3.3 V; 105 °C [11][12]	-	-	3	μA
Standard port pins, $\overline{\text{RESET}}$						
I_{IL}	LOW-level input current	V_I = 0 V; on-chip pull-up resistor disabled	-	0.5	10	nA
I_{IH}	HIGH-level input current	V_I = V_{DD}; on-chip pull-down resistor disabled	-	0.5	10	nA
I_{OZ}	OFF-state output current	V_O = 0 V; V_O = V_{DD}; on-chip pull-up/down resistors disabled	-	0.5	10	nA
V_I	input voltage	pin configured to provide a digital function [13][14][15]	0	-	5.0	V
V_O	output voltage	output active	0	-	V_{DD}	V
V_{IH}	HIGH-level input voltage		0.7V_{DD}	-	-	V



Conditions: BOD disabled; all oscillators and analog blocks disabled in the PDSLEEPCFG register (PDSLEEPCFG = 0x0000 18FF).

Fig 31. Deep-sleep mode: Typical supply current I_{DD} versus temperature for different supply voltages V_{DD} (for LPC111xXL)

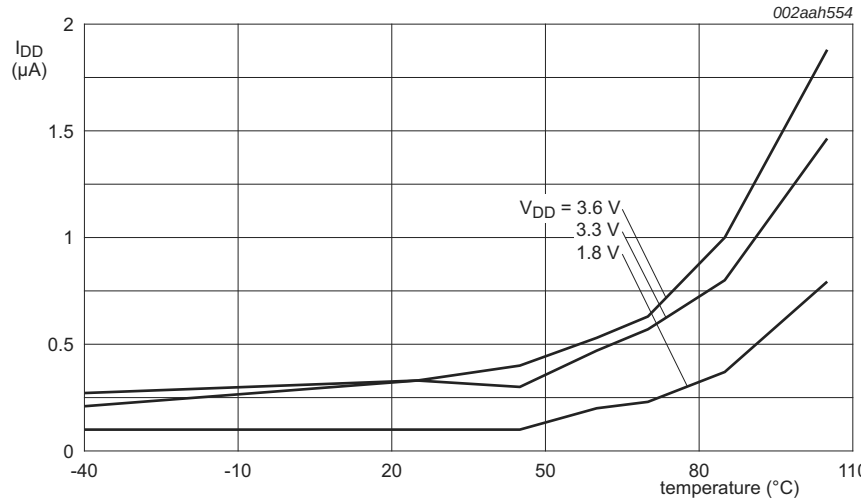
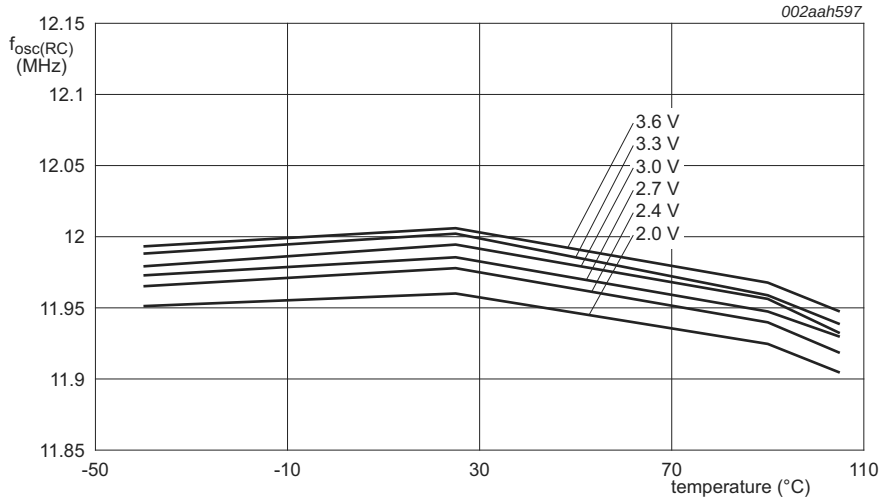


Fig 32. Deep power-down mode: Typical supply current I_{DD} versus temperature for different supply voltages V_{DD} (for LPC111xXL)



Conditions: Frequency values are typical values. 12 MHz ± 1 % accuracy is guaranteed for 2.7 V ≤ V_{DD} ≤ 3.6 V and T_{amb} = −40 °C to +105 °C. Variations between parts may cause the IRC to fall outside the 12 MHz ± 1 % accuracy specification for voltages below 2.7 V.

Fig 45. Internal RC oscillator frequency versus temperature (J parts)

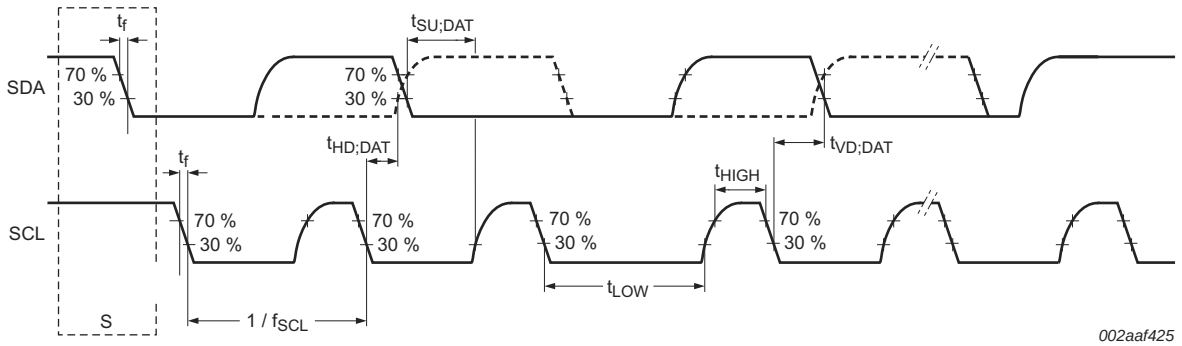


Fig 46. I^2C-bus pins clock timing

11.7 SPI interfaces

Table 29. Dynamic characteristics of SPI pins in SPI mode

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
SPI master (in SPI mode)							
$T_{cy(clk)}$	clock cycle time	full-duplex mode	[1]	50	-	-	ns
		when only transmitting	[1]	40			ns
t_{DS}	data set-up time	in SPI mode	[2]	15	-	-	ns
		2.4 V ≤ V_{DD} ≤ 3.6 V					
		2.0 V ≤ V_{DD} < 2.4 V	[2]	20			ns
		1.8 V ≤ V_{DD} < 2.0 V	[2]	24	-	-	ns
t_{DH}	data hold time	in SPI mode	[2]	0	-	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode	[2]	-	-	10	ns
$t_{h(Q)}$	data output hold time	in SPI mode	[2]	0	-	-	ns
SPI slave (in SPI mode)							
$T_{cy(PCLK)}$	PCLK cycle time			20	-	-	ns
t_{DS}	data set-up time	in SPI mode	[3][4]	0	-	-	ns
t_{DH}	data hold time	in SPI mode	[3][4]	3 × $T_{cy(PCLK)}$ + 4	-	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode	[3][4]	-	-	3 × $T_{cy(PCLK)}$ + 11	ns
$t_{h(Q)}$	data output hold time	in SPI mode	[3][4]	-	-	2 × $T_{cy(PCLK)}$ + 5	ns

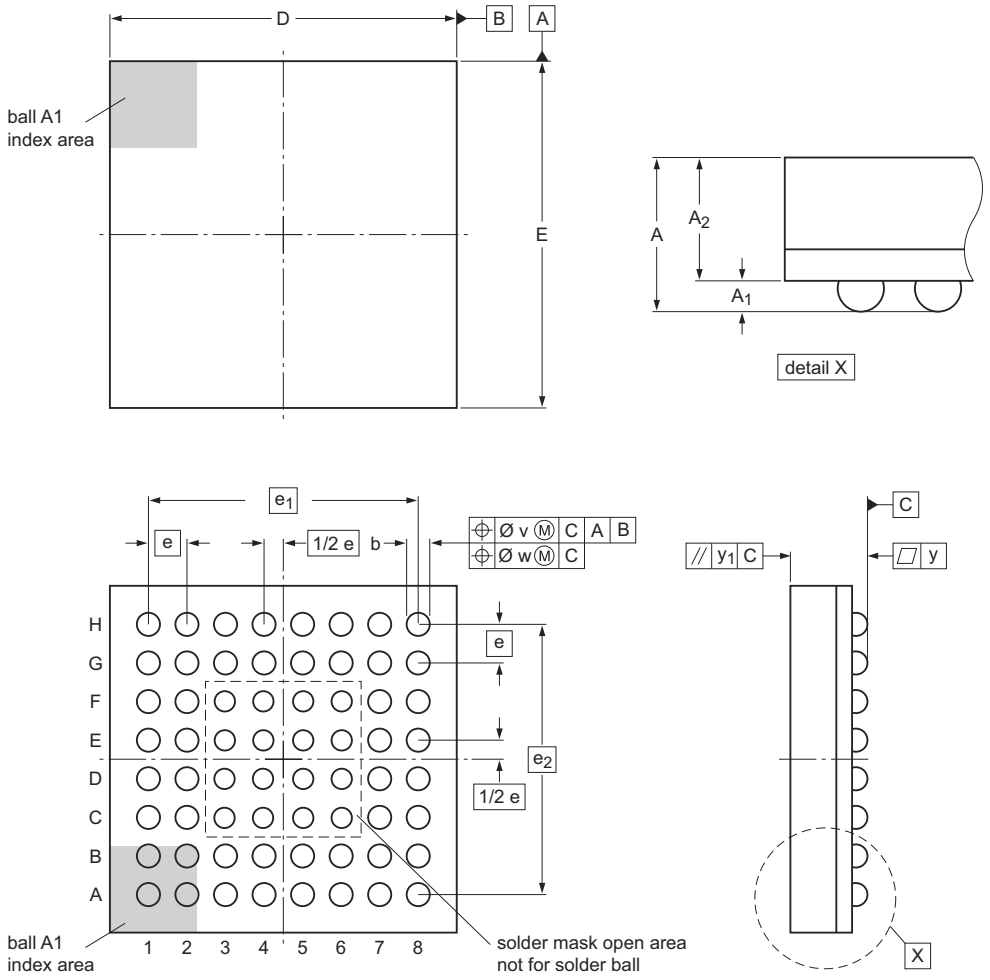
[1] $T_{cy(clk)}$ = (SSPCLKDIV × (1 + SCR) × CPSDVSR) / f_{main}. The clock cycle time derived from the SPI bit rate $T_{cy(clk)}$ is a function of the main clock frequency f_{main}, the SPI peripheral clock divider (SSPCLKDIV), the SPI SCR parameter (specified in the SSP0CR0 register), and the SPI CPSDVSR parameter (specified in the SPI clock prescale register).

[2] T_{amb} = −40 °C to 105 °C.

[3] $T_{cy(clk)}$ = 12 × $T_{cy(PCLK)}$.

[4] T_{amb} = 25 °C; for normal voltage supply range: V_{DD} = 3.3 V.

TFBGA48: plastic thin fine-pitch ball grid array package; 48 balls; body 4.5 x 4.5 x 0.7 mm **SOT1155-2**



Dimensions

Unit	A	A_1	A_2	b	D	E	e	e_1	e_2	v	w	y	y_1
max	1.10	0.30	0.80	0.35	4.6	4.6							
mm nom	0.95	0.25	0.70	0.30	4.5	4.5	0.5	3.5	3.5	0.15	0.05	0.08	0.1
min	0.85	0.20	0.65	0.25	4.4	4.4							

sot1155-2_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1155-2		- - -				~~13-06-17~~ 13-06-19

Fig 62. Package outline TFBGA48 (SOT1155-2)

14. Soldering

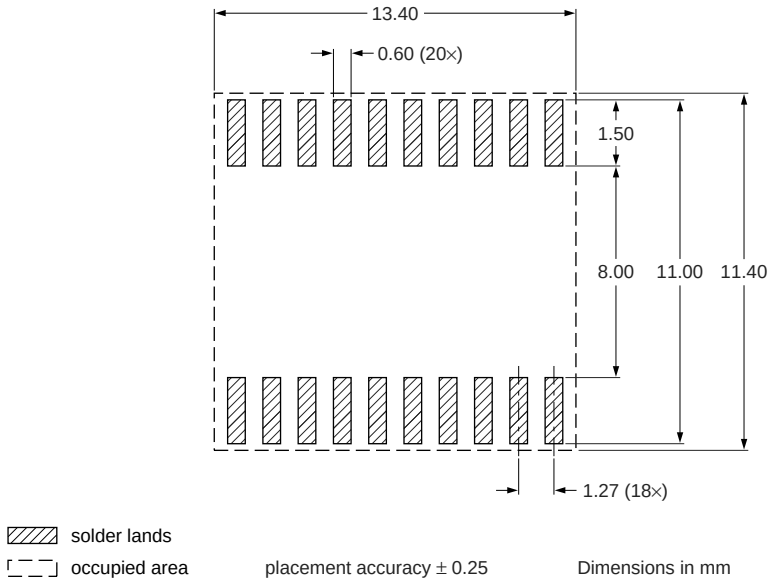


Fig 63. Reflow soldering of the SO20 package

Table 34. Revision history *…continued*

Document ID	Release date	Data sheet status	Change notice	Supersedes
Modifications:	• Power consumption graphs added for parts LPC111x/102/202/302 (Figure 13 to Figure 17). • Parameter V_{hys} for I^2C bus pins: typical value corrected $V_{hys} = 0.05V_{DD}$ in Table 7. • Typical value for parameter N_{endu} added in Table 12 “Flash characteristics”. • I^2C-bus pins configured as standard mode pins, parameter I_{OL} changed to 3.5 mA (minimum) for $2.0\ V \leq V_{DD} \leq 3.6\ V$. • Section 11.6 “ElectroMagnetic Compatibility (EMC)” added. • Power-up characterization added (Section 10.1 “Power-up ramp conditions”).			
LPC1111_12_13_14 v.3	20101110	Product data sheet	-	LPC1111_12_13_14 v.2
Modifications:	• Parts LPC111x/102/202/302 added (LPC1100L series). • Power consumption data for parts LPC111x/102/202/302 added in Table 7. • PLL output frequency limited to 100 MHz in Section 7.15.2. • Description of $\overline{\text{RESET}}$ and WAKEUP functions updated in Section 6. • WDT description updated in Section 7.14. The WDT is a 24-bit timer. • Power profiles added to Section 2 and Section 7 for parts LPC111x/102/202/302.			
LPC1111_12_13_14 v.2	20100818	Product data sheet	-	LPC1111_12_13_14 v.1
Modifications:	• V_{ESD} limit changed to −6500 V (min) /+6500 V (max) in Table 6. • t_{DS} updated for SPI in master mode (Table 17). • Deep-sleep mode functionality changed to allow BOD and watchdog oscillator as the only analog blocks allowed to remain running in Deep-sleep mode (Section 7.15.5.3). • V_{DD} range changed to $3.0\ V \leq V_{DD} \leq 3.6\ V$ in Table 15. • Reset state of pins and start logic functionality added in Table 3 to Table 5. • Section 7.16.1 added. • Section “Memory mapping control” removed. • V_{OH} and I_{OH} specifications updated for high-drive pins in Table 7. • Section 9.4 added.			
LPC1111_12_13_14 v.1	20100416	Product data sheet	-	-

For more information, please visit: http://www.nxp.com
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